





(0.80 mm) .0315"

# POWER/HIGH-SPEED EDGE CARD C

# **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-PV

Insulator Material:

Black Liquid Crystal Polymer Signal Contact:

Power Contact:

Phosphor Bronze

Plating: Au or Sn over 50 µ" (1.27 µm) Ni Operating Temp: -55 °C to +125 °C

**Current Rating:** Signal Pin: 3.2 A per pin (2 pins powered) Power Pin: 27.5 A per pin

(2 pins powered)
RoHS Compliant:

Yes

# **PROCESSING**

Lead-Free Solderable: Yes

# RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

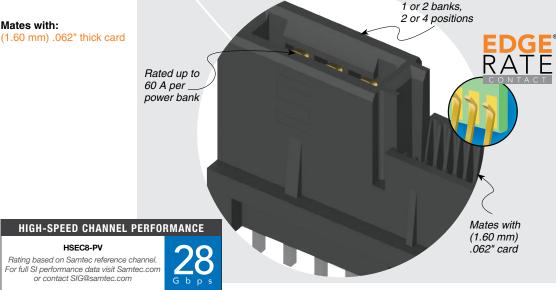


# **APPLICATION**

Some lengths, styles and options are non-standard,

non-returnable.

# Mates with:



HSEC8 POS

**THICKNESS** 

-01

(1.60 mm) .062"

Thick Card

PLATING **OPTION** 

**POS** 

**TAIL** 

**OTHER OPTION** 

-WT

= Weld

Tab

20, 30, 40 (Signal positions per row)

POWER POSITIONS SIGNAL C (-2) В C (-4) A (-2) **A** (-4) (-2)-201.264 (26.20) (52.10) (23.20) (26.20 (40.10) (23.20) -30 .913 1.031 2.051 .913 1.031 (48.10) (31.20) (34.20) (60.10) (31.20) (34.20 -40 1.346 2.366

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

= 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail

-2, -4 (Total, 2 per power bank)

.062" Thick PCB

-2 = Use with (2.36 mm) .0931 Thick PCB

> D (2.35)

.093 (3.13)

D

POWER TAIL

(8.00) - .315 -

= Use with

(1.60 mm)

<b>←</b>	TAIL
[ (8.	00) -15
	_2
(12.00) 472 B (0.80) .0315 →	
	<b>←</b> .
(15,21)	.03)
(15.21) .599	. 1/1 1
	(1.32) .052
$(0.64)  \downarrow  \downarrow  \downarrow  \downarrow  \downarrow  \downarrow  \downarrow  (2.50)$	.12)
$\begin{array}{c} .025 \\ SQ \end{array} \longrightarrow \begin{array}{c} (12.00) \\ .472 \end{array} \longrightarrow \begin{array}{c} (7.50) \\ .295 \end{array} \longrightarrow \begin{array}{c} .098' \\ \end{array} \longrightarrow \begin{array}{c} C \end{array}$	ла (6.56) .161 -

Due to technical progress, all designs, specifications and components are subject to change without notice